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Product Change Notification - JAON-04VUHY153 (Printer Friendly)

Date: 08 Jun 2016
Product Category: SMSC
Notification subject: CCB 1735 Final Notice: Qualification of NSEB as an additional assembly site for selected products in 16L QFN (5x5x0.9mm) package.
Notification text: **PCN Status:**
 Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of NSEB as an additional assembly site for selected products in 16L QFN (5x5x0.9mm) package.

Pre Change:

Assembled at SCC assembly site using C194 lead-frame, 8290 die attach material, G770 molding compound and Palladium coated copper wire with gold flash (CuPdAu) bond wire.

Post Change:

Assembled at NSEB assembly site using EFTEC-64T lead-frame, 8600 die attach material, G700LTD molding compound and palladium coated copper wire with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	SCC assembly site	NSEB assembly site
Wire material	CuPdAu wire	CuPdAu wire
Die attach material	8290	8600
Molding compound material	G770	G700
Lead frame material	C194	EFTEC-64T

Impacts to Data Sheet:

None

Reason for Change:

To improve on-time delivery performance by qualifying NSEB assembly site. SCC assembly site will no longer have manufacturing support to assemble selected products available in 16L QFN (5x5x0.9mm) package.

Change Implementation Status:

In Progress

Estimated First Ship Date:

July 10, 2016 (date code: 1627)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Summary Table:

	September 2015					i >	June 2016					July 2016		
	36	37	38	39	40		22	23	24	25	26	27	28	29
WW														
Initial PCN Issue Date					X									
Qual Report Availability								X						
Final PCN Issue Date								X						
Estimated Implementation Date												X		

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

September 29, 2015: Issued initial notification.

June 8, 2016. Issued final notification. Attached the qualification report. Revised the estimated first ship date from January 22, 2016 to July 10, 2016. Updated the post change to only reflect NSEB assembly site. Updated reason for change to emphasize that SCC will no longer have manufacturing support to assemble selected products available in 16L QFN (5x5x0.9mm) package.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_JAON-04VUHY153_Qual_Report.pdf](#)
- [PCN_JAON-04VUHY153_Affected_CPN.pdf](#)
- [PCN_JAON-04VUHY153_Affected_CPN.xls](#)

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